Application No.: 10/697,561

P27109.A04

CLAIMS

No claims are amended, added, or canceled by this response. For the Examiner's convenience, a copy of all pending claims and a status of the claims is provided below.

- 1. (previously presented) A wood fiberboard, composed of a panel comprising a support board with a top side and an underside, the top side having a decoration, of a wood or tile decoration, wherein the decoration is printed onto the top side of the support board and is covered by at least one layer of a transparent synthetic resin.
- 2. (previously presented) The wood fiberboard, according to Claim 1, wherein the decoration is printed on to the underside of the support board.
- 3. (previously presented) The wood fiberboard, according to Claim 1, wherein the decoration is covered by two layers of a synthetic resin, the layer which is applied directly to the decoration having corundum particles for increasing the abrasion resistance.
- 4. (previously presented) The wood fiberboard, according to Claim 1, wherein the top side has a relief corresponding to the decoration.
- 5. (previously presented) The wood fiberboard, according to Claim 4, wherein the underside also has a relief corresponding to the decoration.

Application No.: 10/697,561

P27109.A04

6. (previously presented) A process for producing a wood fiberboard comprising the following steps:

- a) a decoration, of a wood or tile decoration printed onto one or two sides of the board:
- b) a screen roller is used to spread one or more synthetic-resin layers, of melamineresin or urea-resin layers, on the side with the decoration and the sides located opposite the latter; and
- c) the synthetic-resin layers are pressed with the board.
- 7. (previously presented) The process according to Claim 6, wherein a first of the one or more synthetic-resin layers applied to the decoration is provided with corundum particles.
- 8. (previously presented) The process according to Claim 6, wherein in a short-cyclepress, a relief which corresponds to the decoration provided on a top side is stamped into the synthetic-resin layer.
- (previously presented) The process according to Claim 8, further comprising a relief which corresponds to the decoration provided on an underside is also stamped.
- 10. (previously presented) The process according to Claim 6, wherein the decoration is printed directly onto at least one of a top side and an underside of the board.
- 11. (previously presented) The process according to Claim 6, wherein floor panels are sawn from the wood fiberboard.
- 12. (previously presented) The process according to Claim 8, wherein floor panels are sawn from the wood fiberboard.

Application No.: 10/697,561

P27109.A04

13. (previously presented) The process according to Claim 10, wherein floor panels are

sawn from the wood fiberboard.

14. (previously presented) The wood fiberboard, according to Claim 4, wherein the

decoration is covered by two layers of a synthetic resin, the layer which is applied

directly to the decoration having corundum particles for increasing the abrasion

resistance.

15. (previously presented) The wood fiberboard, according to Claim 2, wherein the top

side has a relief corresponding to the decoration.

16. (previously presented) The wood fiberboard, according to Claim 3, wherein the top

side has a relief corresponding to the decoration.

17. (previously presented) The process according to claim 6, wherein the wood

fiberboard comprises an HDF support board with a top side and an underside, the top

side having a decoration of a wood or tile decoration, wherein the decoration is printed

onto the top side of the support board and is covered by at least one layer of a

transparent synthetic resin.

18. (previously presented) The process according to claim 6, wherein the decoration is

printed on to an underside of the board.

19. (previously presented) The wood fiberboard, according to Claim 1, wherein the

decoration is printed directly on the top side of the support board.

20. (previously presented) The wood fiberboard, according to Claim 1, wherein the

support board is composed of HDF.